

Product / Package Information

| | |
|-----------------|-------------|
| Package | TQFP |
| Body Size (mm) | 7 X 7 X 1.0 |
| Lead Count | 32 |
| Terminal Finish | NiPdAu |
| MS Number | MS012094B |

Environmental Information

| | |
|----------------------------|-----------|
| RoHS Compliant | Yes |
| High Temperature Compliant | Yes |
| Halogen Free Compliant | Yes |
| REACH SVHC Compliant | Yes |
| Last Updated | 11-Jul-19 |

Materials Declaration

Molding Compound

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|--------------|-------------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Silica | 60676-86-0 | 1.23E-01 | 87.00 | 870000 | 42.87 | 428701 |
| Thermosets | Epoxy Resin | Proprietary | 1.06E-02 | 7.50 | 75000 | 3.70 | 36957 |
| Thermosets | Phenol Resin | Proprietary | 7.05E-03 | 5.00 | 50000 | 2.46 | 24638 |
| Other inorganic materials | Carbon black | 1333-86-4 | 7.05E-04 | 0.50 | 5000 | 0.25 | 2464 |
| Subtotal | | | 1.41 E-01 | 100.00 | 1000000 | 49.28 | 492760 |

Leadframe

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------|------------|-----------|------------|----------------------------|---------|-----------------|--------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 1.01E-01 | 97.50 | 975000 | 35.14 | 351405 |
| Copper & its alloys | Iron | 7439-89-6 | 2.42E-03 | 2.35 | 23500 | 0.85 | 8470 |
| Copper & its alloys | Zinc | 7440-66-6 | 1.24E-04 | 0.12 | 1200 | 0.04 | 432 |
| Copper & its alloys | Phosphorus | 7723-14-0 | 3.09E-05 | 0.03 | 300 | 0.01 | 108 |
| Subtotal | | | 1.03 E-01 | 100.00 | 1000000 | 36.04 | 360415 |

External Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------|-----------|-----------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Nickel & its alloys | Nickel | 7440-02-0 | 4.48 E-03 | 88.26 | 882600 | 1.57 | 15669 |
| Precious Metals | Palladium | 7440-05-3 | 2.66 E-04 | 5.24 | 52400 | 0.09 | 930 |
| Precious Metals | Gold | 7440-57-5 | 3.30 E-04 | 6.50 | 65000 | 0.12 | 1154 |
| Subtotal | | | 5.08E-03 | 100.0 | 1000000 | 1.78 | 17753 |

Bond Wires

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|-----------------|-----------|-----------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious Metals | Gold | 7440-57-5 | 4.87E-03 | 99.0 | 990000 | 1.70 | 17024 |
| Precious Metals | Palladium | 7440-05-3 | 4.92E-05 | 1.00 | 10000 | 0.02 | 172 |
| Subtotal | | | 4.92E-03 | 100.00 | 1000000 | 1.72 | 17196 |

Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|---------------|-----------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 2.78E-02 | 100.0 | 1000000 | 9.73 | 97257 |

Die Attach

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---------------------------|------------------|--------------|------------|----------------------------|---------|-----------------|-------|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Silver | 7440-22-4 | 2.51E-03 | 60 | 600000 | 0.88 | 8772 |
| Other inorganic materials | Silica | Trade secret | 4.18E-04 | 10 | 100000 | 0.15 | 1462 |
| Other inorganic materials | Allyl compound | Trade secret | 3.14E-04 | 7.5 | 75000 | 0.11 | 1096 |
| Other organic materials | Epoxy resin A | 9003-36-5 | 1.05E-04 | 2.5 | 25000 | 0.04 | 365 |
| Other organic materials | Epoxy resin B | Trade secret | 1.46E-04 | 3.5 | 35000 | 0.05 | 512 |
| Other organic materials | Diluent A | Trade secret | 1.05E-04 | 2.5 | 25000 | 0.04 | 365 |
| Other organic materials | Diluent B | Trade secret | 1.46E-04 | 3.5 | 35000 | 0.05 | 512 |
| Other organic materials | Hardener | Trade secret | 1.46E-04 | 3.5 | 35000 | 0.05 | 512 |
| Other organic materials | Dicyandiamide | 461-58-5 | 1.46E-04 | 3.5 | 35000 | 0.05 | 512 |
| Other organic materials | Organic peroxide | Trade secret | 1.46E-04 | 3.5 | 35000 | 0.05 | 512 |
| Subtotal | Subtotal | | 4.18 E-03 | 100.00 | 1000000 | 1.46 | 14620 |

| | | | | | | | |
|-----------------------|--|--|-------------------|--|--|-----------------------|------------|
| Package Totals | | | Weight (g) | | | Percentage (%) | PPM |
| | | | 2.86 E-01 | | | 100.00 | 1000000 |

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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